

Amendments to the Claims:

This listing of claims will replace all prior versions and listing of claims in the application.

Claim 22 is amended.

Listing of Claims:

1. (Original) A wiring board, comprising:
 - a plurality of conductive layers each including one or more wirings for transmitting signals; and
 - a plurality of insulation layers for insulating the respective conductive layers; wherein the conductive layers and the insulation layers are laminated alternately, and
 - each of the plurality of conductive layers is provided with a terminal at at least one of both ends,
 - wherein the terminals are formed stepwise and separated by the insulation layers in a cross-sectional shape of a lamination structure of the conductive layers and the insulation layers.
2. (Original) The wiring board according to claim 1, wherein the conductive layers and the insulation layers are formed in an atmosphere at a reduced pressure below the atmospheric pressure.
3. (Original) The wiring board according to claim 1, wherein the plurality of conductive layers are three or more thin film conductive layers.

4. (Original) The wiring board according to claim 1, wherein one or more conductive layers among the plurality of conductive layers comprise a plurality of wirings.
5. (Original) The wiring board according to claim 1, wherein the number of wirings included in one of the plurality of conductive layers and the number of wirings included in another conductive layer of the plurality of conductive layers are different from each other.
6. (Original) The wiring board according to claim 1, wherein at least two conductive layers among the plurality of conductive layers comprise a shield layer for shielding a wiring in another conductive layer sandwiched between the two conductive layers.
7. (Original) The wiring board according to claim 1,
wherein one or more conductive layers among the plurality of conductive layers comprise a plurality of wirings, and
each of the plurality of wirings comprises the terminal.
8. (Original) The wiring board according to claim 1, wherein the terminals are arranged stepwise from a conductive layer laminated at the center toward conductive layers on both sides.

9. (Original) The wiring board according to claim 1, wherein the terminals are arranged in any one of manners that are along one vertical line, along one horizontal line and in a matrix form, when viewing from a lamination direction of the conductive layers and the insulation layers.
10. (Original) The wiring board according to claim 1, wherein the terminals are arranged along a direction oblique to a longitudinal direction of the wirings, when viewing from a lamination direction of the conductive layers and the insulation layers.
11. (Original) The wiring board according to claim 1, wherein the terminals are arranged in a V-letter shape, when viewing from a lamination direction of the conductive layers and the insulation layers.
12. (Original) The wiring board according to claim 1, wherein the terminals each have a thickness larger than the conductive layer that is covered with the insulation layer.
13. (Original) The wiring board according to claim 1, wherein bumps are formed on the respective terminals.
14. (Original) The wiring board according to claim 13,
wherein each of the bumps has an electric connection face at its tip end, and
the respective electric connection faces are formed to be coplanar.

15. (Original) The wiring board according to claim 1, further comprising:
a protective layer that covers the terminals;
via hole conductors that are formed in the protective layer and connect with the respective terminals; and
a plurality of electrodes that are formed on a surface of the protective layer and connect with the respective via hole conductors.
16. (Original) The wiring board according to claim 1,
wherein each of the terminals is formed so as to protrude and has an electric connection face at its tip end, and
the respective electric connection faces are formed so as to be coplanar.
17. (Original) The wiring board according to claim 1, wherein the conductive layers and the insulation layers are formed by at least one of a vapor deposition method, a sputtering method and a CVD method.
18. (Original) A method for manufacturing a wiring board, the wiring board comprising: a plurality of conductive layers each including one or more wirings for transmitting signals; and a plurality of insulation layers for insulating the respective conductive layers; wherein the conductive layers and the insulation layers are laminated alternately, and each of the plurality of conductive layers is provided with a terminal at at least one of both ends,

wherein the method comprises the step of forming the terminals stepwise and separated by the insulation layers in a cross-sectional shape of a lamination structure of the conductive layers and the insulation layers.

19. (Original) The method for manufacturing a wiring board according to claim 18, wherein the terminals are formed by plating while feeding electricity to the conductive layers at one end.

20. (Original) The method for manufacturing a wiring board according to claim 18, wherein each of the terminals is made up of a bump, wherein masking is applied to the conductive layers at one end using a mask having an aperture, and the bumps are formed by plating through the aperture of the mask while feeding electricity to the masked conductive layers at the one end.

21. (Original) The method for manufacturing a wiring board according to claim 18, wherein each of the terminals is made up of a bump, and the bumps are formed by depositing a conductor at one end of the conductive layers.

22. (Currently Amended) The method for manufacturing a wiring board according to claim 20 or 21, wherein a pressure is applied to tip ends of the respective bumps with flat plates so that the bumps are uniform in height to be coplanar.

23. (Original) A method for manufacturing a wiring board, the wiring board comprising: a plurality of conductive layers each including one or more wirings for transmitting signals; and a plurality of insulation layers for insulating the respective conductive layers, wherein the conductive layers and the insulation layers are laminated alternately,

wherein the method comprises the step of forming the conductive layers and the insulation layers in an atmosphere at a reduced pressure below the atmospheric pressure.

24. (Original) Electronic equipment, comprising:

a plurality of circuit boards; and

a wiring board that connects the circuit boards,

wherein the wiring board is one according to claim 1.